

# Different Wavelength Photon Emissions from Group-IV-Semiconductor Quantum-Dots Fabricated by Hot-Ion Implantation Technique

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## Abstract

We experimentally studied three types of group-IV-semiconductor quantum-dots (IV-QDs) of Si-, SiC-, and C-QDs in Si-oxide (OX) layer fabricated by very simple process of hot-ion implantation technique of Si<sup>+</sup>, double Si<sup>+</sup>/C<sup>+</sup>, and C<sup>+</sup> into OX, respectively, to realize a different wavelength PL emission from near-IR to near-UV ranges. TEM analyses newly confirmed both Si- and C-QDs with a diameter of ~2nm in OX. We can successfully demonstrate very strong PL emission from three IV-QDs, and the peak photon energies  $E_{PH}$  (peak wavelength) of Si-, and SiC-, and C-QDs were approximately 1.56eV (880nm), 2.5eV (500nm), and 3.3eV (380nm), respectively. IV-QDs showed that PL properties strongly depend on the hot-ion doses of Si and C atoms and the post N<sub>2</sub> annealing processes. Consequently, it is easily possible for IV-QDs to design peak PL emission wavelength by controlling the ion doses of Si<sup>+</sup> and C<sup>+</sup> implanted into OX layer.

## I. Introduction

Using the self-clustering effects of hot ion-implanted C atoms in Si layer [1], 3C-SiC and hexagonal-SiC (H-SiC) nano-dots (diameter  $R \approx 2\text{nm}$ ) can be easily formed in various Si crystal structures from amorphous to crystal Si by hot-C<sup>+</sup>-ion implantation technique [2], [3]. We demonstrated very strong PL emission  $I_{PL}$  in near-UV/visible regions (>400nm) from indirect-bandgap SiC-dots, which is attributable to free exciton recombination of excited electrons in SiC-dots [4]. However, since the SiC dots with larger bandgap  $E_G$  (>2.4eV) are embedded in Si layer with smaller  $E_G$  ( $\approx 1.1\text{eV}$ ), the SiC-dots in Si layer is not a quantum-dot (QD), resulting in too small PL quantum efficiency for visible Si-based photonic devices. Thus, we experimentally realized SiC-QDs embedded in SiO<sub>2</sub> (OX) with large  $E_G \approx 9\text{eV}$ , using double hot-Si<sup>+</sup>/C<sup>+</sup>-ion implantation into an OX [5]. We successfully confirmed that the PL quantum efficiency of SiC-QDs is 2.5 times higher than that of SiC-dots in Si, because of enlarged life time of electrons which are quantum mechanically confined in SiC-QDs [5]. Thus, to realize different wavelength photonic devices from IR to UV range, QD structures with various  $E_G$ , such as Si- and C-QDs except SiC-QDs are strongly required, too. C- and Si-QDs have been widely studied [6], [7], but have been not realized by very simple and ULSI compatible processes of hot-ion implantation technique, yet.

In this work, we experimentally studied group-IV-semiconductor QDs (IV-QDs) of Si-, SiC-, and C-QDs, using very simple processes of hot-ion implantation into OX layer and the post N<sub>2</sub> annealing. We successfully demonstrated very strong PL emissions with different peak photon energies  $E_{PH}$  from Si-QDs (near-IR (NIR)) by Si<sup>+</sup> hot-implantation, SiC-QDs (visible range) by double Si<sup>+</sup>/C<sup>+</sup> hot-implantation [5], and C-QDs (near-UV) by C<sup>+</sup> hot-implantation.

## II. Experiment Procedure

Using the simple fabrication processes of hot-ion implantation into an OX layer and post N<sub>2</sub> annealing [5], we realized three types of IV-QDs (Si-, SiC-, and C-QDs) in OX layer. For example, Si-QDs (Si<sup>+</sup>-OX) were fabricated by hot-Si<sup>+</sup> implantation into the OX layer on (100) bulk-Si substrate at substrate temperature  $T$  (600°C) (Fig.1(b)) after forming 140-nm thick OX by dry O<sub>2</sub> of Si (Fig.1(a)). Post N<sub>2</sub> annealing was carried out at annealing temperature  $T_N = 1000^\circ\text{C}$  for various annealing time  $t_N$  (Fig.1(c)). Moreover, SiC- (Si<sup>+</sup>/C<sup>+</sup>-OX) and C-QDs (C<sup>+</sup>-OX) were also fabricated by double hot Si<sup>+</sup>/C<sup>+</sup> and single hot C<sup>+</sup> implantation into OX [5] at various  $T$ , respectively, instead of single hot Si<sup>+</sup> ion implantation in Si-QDs (Fig.1(b)). In this study, hot-ion dose conditions of Si<sup>+</sup> ( $D_S$ ) and C<sup>+</sup>-ion doses ( $D_C$ ) were varied from  $4 \times 10^{16}$  to  $1 \times 10^{17} \text{ cm}^{-2}$  for increasing the PL intensity of IV-QDs.

PL and Raman properties of IV-QDs were measured at room temperature, where the excitation laser energy and diameter were 3.8eV and 1μm, respectively. The wide photon wavelength  $\lambda_{PL}$  PL spectrum from the near-UV (NUV) to NIR regions was calibrated using a standard illuminant.

## III. Results and Discussions

### A. Material Structures of IV-QDs

The depth profiles of implanted atom concentration in IV-QDs was evaluated by XPS, and the peak Si at  $D_S = 6 \times 10^{16} \text{ cm}^{-2}$  and C concentrations at  $D_C = 4 \times 10^{16} \text{ cm}^{-2}$  were approximately  $6 \times 10^{21}$  and  $4 \times 10^{21} \text{ cm}^{-3}$ , respectively (Fig.2). We successfully confirmed many Si- (Fig.3(a)) and C-QDs (Fig.3(b)) in OX by HAADF-STEM, too, and SiC-QDs were already verified in our previous work [5]. Moreover, clear lattice spots of SiC-, Si-, and C-QDs can be observed by CSTEM (Fig.4). The average diameters  $R$  of IV-QDs were approximately 2-4nm (Fig.5). Moreover, IV-QD densities  $N$  were around  $2 \times 10^{12} \text{ cm}^{-2}$  (Fig.5).

### B. Raman Properties

UV-Raman of Si-QDs shows that an a-Si Raman peak decreases with increasing  $t_N$  (Fig.6(a)), which indicates that the crystal quality of Si-QD can be improved by N<sub>2</sub> annealing. Moreover, the G- and D-bands of C-C vibrations in C-QDs also increases with increasing  $t_N$  (Fig.6(b)), and thus graphite-based C-QD quality also increases after N<sub>2</sub> annealing. The Raman spectrum of SiC-QDs strongly depends on the dopant ratio of  $D_S/D_C$ , and both the TO of Si-C vibration and D-band intensity increase with decreasing  $D_S/D_C$  even at the same  $D_C$  (Fig.7).

### C. PL Properties

We experimentally demonstrated the different  $E_{PH}$  ( $\lambda_{PL}$ ) emissions from C-QDs (NUV), SiC-QDs (visible region), and Si-QDs (NIR) (Fig.8). The  $I_{PL}$  of SiC-QDs was largest, and approximately 2.5 and 7.0 times as large as that of Si- and C-QDs, respectively. Moreover, Si-QDs shows very sharp PL spectrum with FWHM of 0.23eV, compared with broad PL spectra of SiC- (0.85eV) and C-QDs (0.89eV). Consequently, it is easily possible for IV-QDs to control PL emission wavelength from NIR to NUV by changing the atom implanted into OX.

The peak- $I_{PL}$ ;  $I_{MAX}$  of IV-QDs rapidly increases after short N<sub>2</sub> annealing (Fig.9), which is possibly attributable to the increase of the improved crystal quality of IV-QDs (Figs.6(a), 6(b)). In addition, even at the high- $T_N$  annealing, the  $I_{MAX}$  of IV-QDs does not degrade after long  $t_N$ , which was confirmed even at  $T_N = 1200^\circ\text{C}$ . However, SiC-dots in Si layer (dotted line in Fig.9) shows the drastic decrease of  $I_{MAX}$  with increasing  $t_N$  at  $T_N \geq 900^\circ\text{C}$ , which suggests that SiC-dots in Si is thermally unstable [3]. Thus, IV-QD structures have thermal stability in  $T_N$  of lower than at least  $1200^\circ\text{C}$ , which is the advantageous characteristic of QDs in OX.

The  $I_{MAX}$  and  $E_{PH}$  ( $\lambda_{PL}$ ) of Si- and C-QDs also depend on  $D_S$  and  $D_C$ , respectively (Fig.10). With increasing the ion dose, the  $I_{MAX}$  of Si-QDs decreases, but the  $I_{MAX}$  of C-QDs increases. In addition, the  $E_{PH}$  of Si-QD is almost independent of  $D_S$ , but the  $E_{PH}$  of C-QDs increases with increasing the  $D_C$ .

On the other hand, the PL spectrum of SiC-QDs strongly depend on the  $D_S/D_C$  ratio even at fixed  $D_C$  (Fig.11). Namely, the  $I_{MAX}$  of SiC-QDs rapidly decreases at  $D_S/D_C = 2$ , because of reduced Si-C bonding (Fig.7). In addition, the  $E_{PH}$  of SiC-QD decreases with increasing  $D_S/D_C$ .

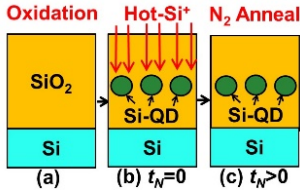
Consequently, the peak- $\lambda_{PL}$  of IV-QDs from NUV to NIR regions can be easily designed by  $D_S$  and  $D_C$  conditions (Fig.12). Namely, shorter or longer  $\lambda_{PL}$  emissions of IV-QDs can be achieved by increasing  $D_C$  or  $D_S$ , respectively (Fig.12).

## IV. Conclusion

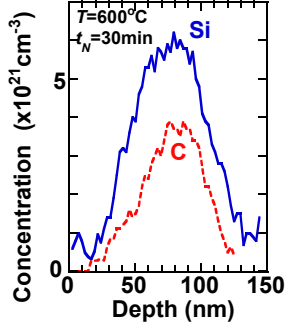
In this work, we experimentally studied group-IV semiconductor QDs (Si-, SiC-, and C-QDs) in OX layer, fabricated by hot-ion implantation and the post N<sub>2</sub> annealing. We demonstrated very strong PL emissions from IV-QDs with different  $\lambda_{PL}$  of NIR from Si-QDs, visible range from SiC-QDs, and NUV from C-QDs. Thus, it is easily possible for IV-QDs to design peak- $\lambda_{PL}$  by controlling ion doses of Si, Si/C, and C implanted into OX layer.

**Acknowledgement:** This work was partially supported by KAKENHI (17K06359).

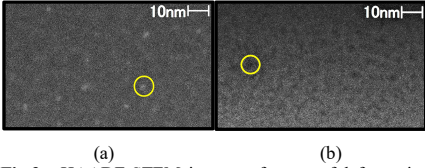
**References:** [1] T.Mizuno, JJAP 57, 04FB03, 2018. [2] T.Mizuno, JJAP 58, SBBJ01, 2019. [3] T.Mizuno, JJAP 58, 081004, 2019. [4] J.Fan, Silicon Carbide Nanostructures (Springer), 2014. [5] T.Mizuno, JJAP 59, SSGH02, 2020. [6] N.Yang, Carbon Nanoparticles and Nanostructures, (Springer), 2016. [7] L.Pavesi, Silicon Nanocrystal, (Wiley-VCH), 2010.



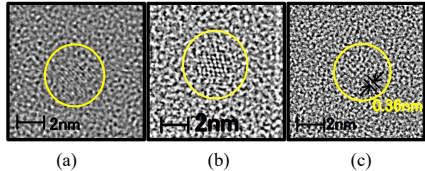
**Fig.1** Si-QD fabrication steps in Si<sup>+</sup>-OX by hot-Si<sup>+</sup>-ion-implantation into SiO<sub>2</sub> layer. After (a) dry-oxidation process of bulk-Si substrate, (b) hot-Si<sup>+</sup>-ions with  $D_S$  were implanted into SiO<sub>2</sub> layer at  $T$ . (c) Post N<sub>2</sub> annealing was carried out at  $T_N$  for  $t_N$ .



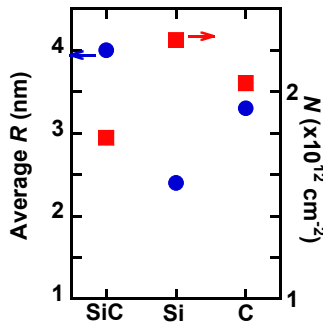
**Fig.2** Concentration depth profiles of implanted Si (solid line) at  $D_S=6 \times 10^{16} \text{ cm}^{-2}$  or C (dashed line) atoms at  $D_C=4 \times 10^{16} \text{ cm}^{-2}$  in SiO<sub>2</sub> layer, which was evaluated by Si2p and C1s spectra of XPS, respectively, where  $T=600^\circ\text{C}$  and  $t_N=30\text{min}$ .



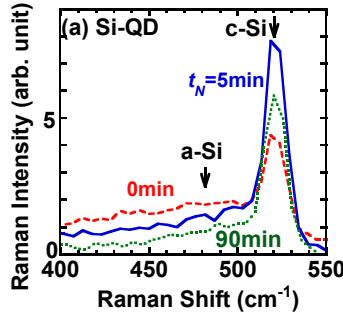
**Fig.3** HAADF-STEM images of successful formation of many (a) Si-QDs (encircled bright spot) at  $D_S=6 \times 10^{16} \text{ cm}^{-2}$ ,  $T=600^\circ\text{C}$  and  $t_N=60\text{min}$ , and (b) C-QDs (encircled dark spot) at  $D_C=1 \times 10^{17} \text{ cm}^{-2}$ ,  $T=400^\circ\text{C}$  and  $t_N=30\text{min}$ .



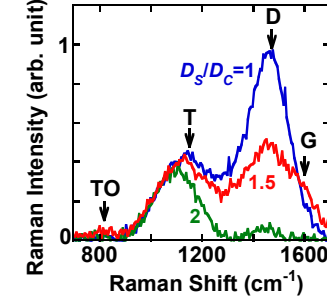
**Fig.4** CSTEM lattice images of (a) hexagonal-SiC-QD at  $D_S=6 \times 10^{16} \text{ cm}^{-2}$ ,  $D_C=4 \times 10^{16} \text{ cm}^{-2}$ ,  $T=400^\circ\text{C}$ , and  $t_N=30\text{min}$ , (b) Si-QD, and (c) C-QD. Process conditions of (b) and (c) are the same of Fig.3. The lattice distance of C-atoms in (c) was approximately 0.36nm, which is nearly equal to the layer distance of graphite (0.335nm).



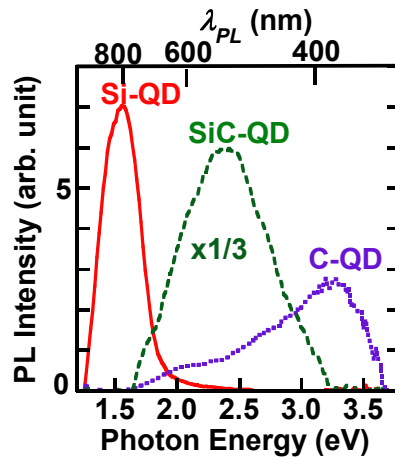
**Fig.5** Average  $R$  (circles) and  $N$  (squares) of SiC-QDs ( $D_S=6 \times 10^{16} \text{ cm}^{-2}$ ,  $D_C=4 \times 10^{16} \text{ cm}^{-2}$ ,  $T=600^\circ\text{C}$ , and  $t_N=30\text{min}$ ), Si-QDs and C-QDs. Process conditions of Si- and C-QDs are the same as those of Fig.3.



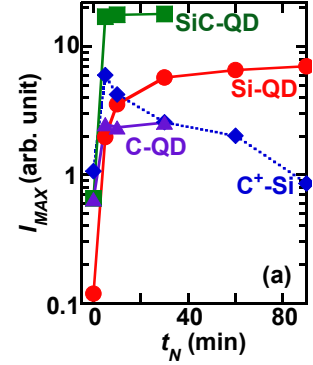
**Fig.6**  $t_N$  dependence of UV-Raman spectra of (a) Si-QD at  $D_S=6 \times 10^{16} \text{ cm}^{-2}$ , and (b) C-QD at  $D_C=1 \times 10^{17} \text{ cm}^{-2}$ , where  $T=600^\circ\text{C}$ . The arrows in (a) show the peak Raman shifts of c-Si ( $520 \text{ cm}^{-1}$ ) and a-Si ( $480 \text{ cm}^{-1}$ ). The arrows in (b) show the T, D, and G bands of C-C vibration.



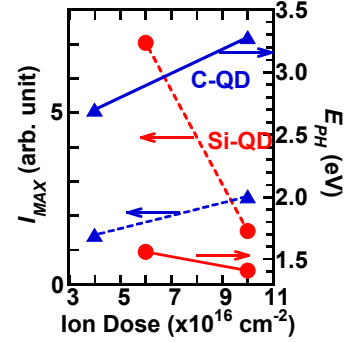
**Fig.7**  $D_S/D_C$ -ratio dependence of Raman spectra of SiC-QD at fixed  $D_C=4 \times 10^{16} \text{ cm}^{-2}$ , where  $T=200^\circ\text{C}$ , and  $t_N=0$ . The arrows show the G, D and T bands of C-C vibrations, and the TO mode of Si-C vibration.



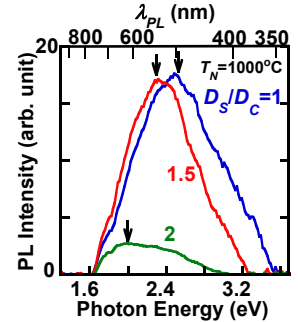
**Fig.8** PL spectrum comparison between Si-QD (solid line:  $D_S=6 \times 10^{16} \text{ cm}^{-2}$ ,  $T=600^\circ\text{C}$ ,  $t_N=1.5\text{h}$ ), SiC-QD (dashed line:  $D_S=6 \times 10^{16} \text{ cm}^{-2}$ ,  $D_C=4 \times 10^{16} \text{ cm}^{-2}$ ,  $T=200^\circ\text{C}$ ,  $t_N=30\text{min}$ ), and C-QD (dotted line:  $D_C=1 \times 10^{17} \text{ cm}^{-2}$ ,  $T=600^\circ\text{C}$ ,  $t_N=30\text{min}$ ). The lower and upper axes show the PL photon energy and wavelength, respectively. The PL intensity of SiC-QD shows 1/3 times as large as measured PL data.



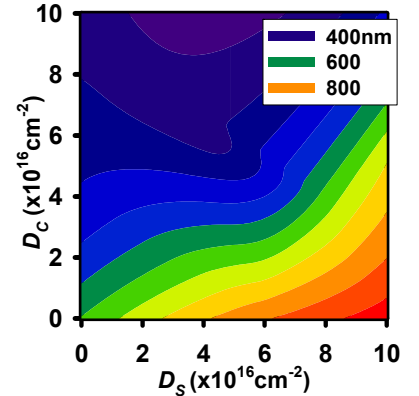
**Fig.9**  $t_N$  dependence of  $I_{MAX}$  as the same data of Fig.8 (Si-QD (circles), SiC-QD (squares), and C-QD (triangles)). Rhombi show the data of SiC dots in Si layer (C<sup>+</sup>-Si).



**Fig.10** Ion dose dependence of  $I_{MAX}$  (dashed lines) and  $E_{PH}$  (solid lines) of Si-QD (circles) and C-QD (triangles) after N<sub>2</sub> annealing, where  $T=600^\circ\text{C}$ .



**Fig.11**  $D_S/D_C$ -ratio dependence of PL spectrum of SiC-QD at  $t_N=5\text{min}$ , where  $D_C=4 \times 10^{16} \text{ cm}^{-2}$  and  $T=200^\circ\text{C}$ . Arrows show the  $E_{PH}$  positions.



**Fig.12**  $D_S/D_C$  conditions for designing peak- $\lambda_{PL}$  of IV-QDs. This contour map of peak- $\lambda_{PL}$  was obtained by the data of Figs. 8, 10, and 11.